



# 7<sup>th</sup> IEEE Electron Devices Technology and Manufacturing (EDTM) Conference 2023

March 7 – 10, 2023 / COEX Seoul, Korea

## 15A. Advanced Fan-Out Package

|                       |   |
|-----------------------|---|
| <b>Session Date:</b>  | March 8(Wed.), 2023                     |
| <b>Session Time:</b>  | 15:15-16:50                             |
| <b>Session Room:</b>  | Room A (#301)                           |
| <b>Session Chair:</b> | Prof. Hak-Sung Kim (Hanyang university) |

**[15A-1] [Invited]**

**15:15-15:40**

### A Closer Look to Fan-out Panel Level Packaging

Tanja Braun<sup>1</sup>, Ole Hölck<sup>2</sup>, Marcus Voitel<sup>2</sup>, Mattis Obst<sup>1</sup>, Steve Voges<sup>1</sup>, Karl-Friedrich Becker<sup>1</sup>, Rolf Aschenbrenner<sup>1</sup> and Martin Schneider-Ramelow<sup>2</sup>

<sup>1</sup>Fraunhofer Institute for Reliability and Microintegration, <sup>2</sup>Technical University of Berlin

**[15A-2] [Invited]**

**15:40-16:05**

### Status of the Advanced Packaging and IC Substrate

Yik-Yee Tan

*Yole Intelligence*

**[15A-3]**

**16:05-16:20**

### Enhancing Predictability of Thermal Warpage of Molded Wafer by Applying Accurate Thermo-Mechanical Properties of Molded Underfill

Junmo Kim<sup>1</sup>, Myoung Song<sup>1</sup>, Chang-Yeon Gu<sup>1</sup>, Sung Woo Ma<sup>2</sup>, Mu-Hyeon Jeong<sup>2</sup>, Jin Hee Lee<sup>2</sup>, Woong-Sun Lee<sup>2</sup> and Taek-Soo Kim<sup>1</sup>

<sup>1</sup>Korea Advanced Institute of Science and Technology, <sup>2</sup>SK hynix Inc.

**[15A-4]**

**16:20-16:35**

### A Noble VFO (Vertical wire Fan Out) Technology for Small Form Factor and High Performance Memory Applications

Ki-Jun Sung, Kyoungtae Eun, Seowon Lee, Sungwon Yoon, Ho-Young Son and Kang-Wook Lee  
*SK hynix Inc.*

**[15A-5]**

**16:35-16:50**

### Development of Curing Process for EMC to Reduce the Warpage of Semiconductor Package

Seong Yeon Park and Seong Su Kim

*Korea Advanced Institute of Science and Technology*